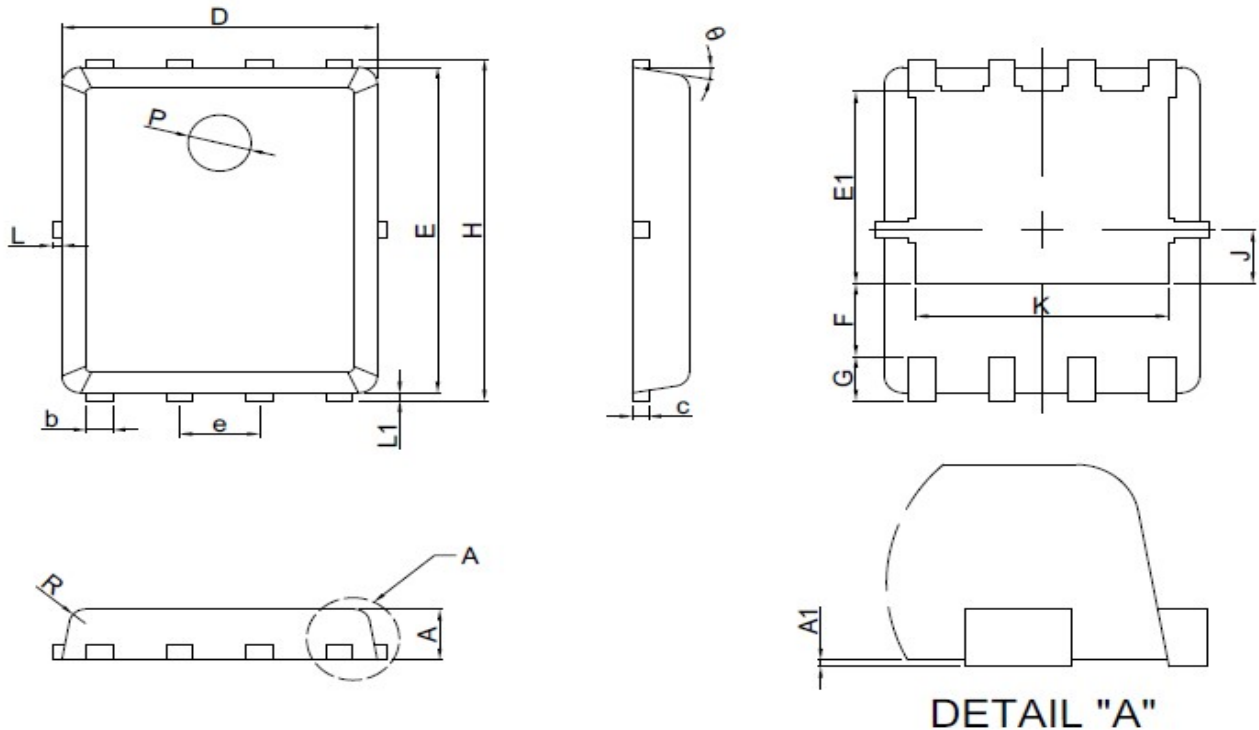


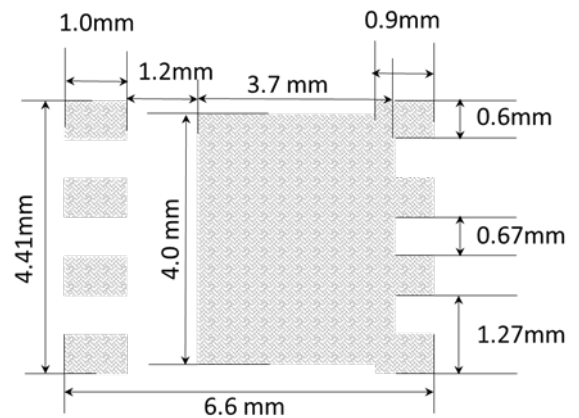
Package Dimensions : PDFN5x6_K8001



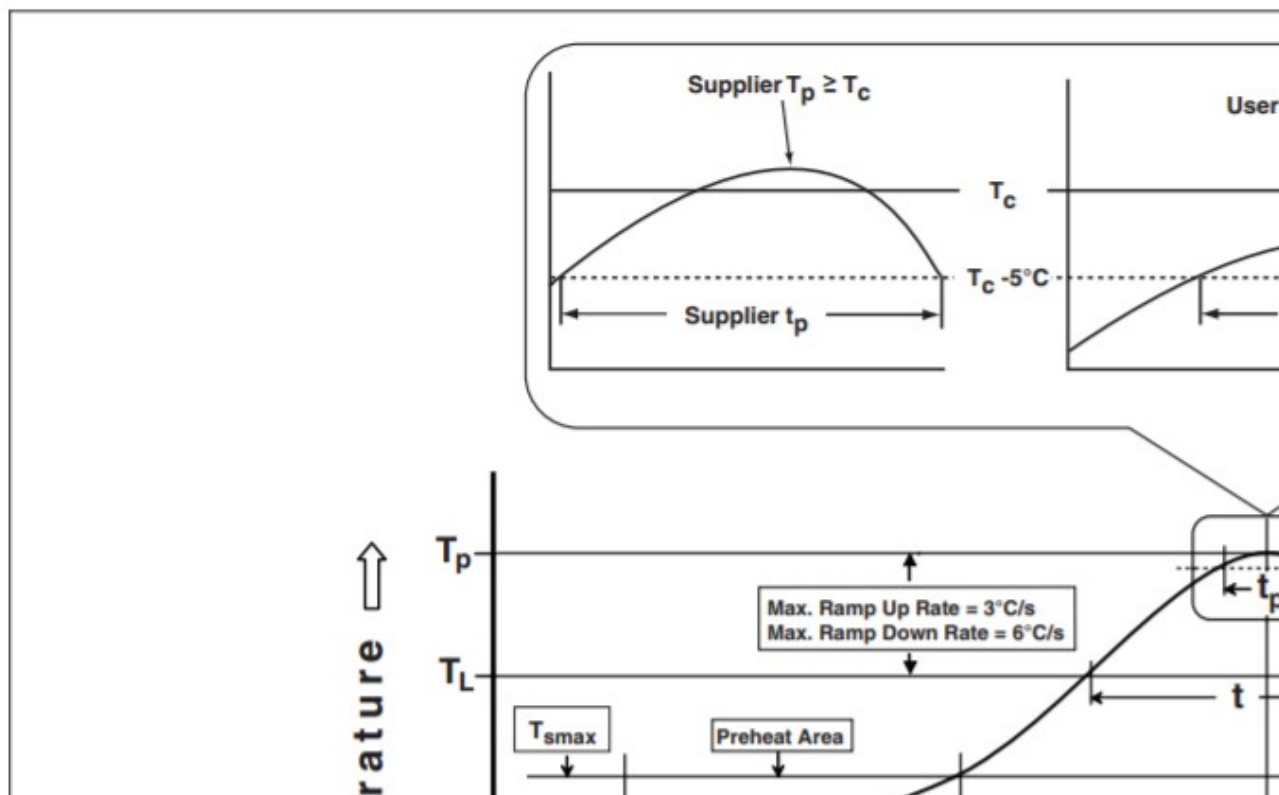
Unit:mm

	Min	Typ	Max
A	0.800	/	1.100
A1			
b	0.350	/	0.510
c	0.254 REF		
D	4.800	/	5.100
F	1.4 REF		
E	5.674	/	5.900
e	1.27 BSC		
H	5.950	/	6.200
L1	/	/	/
G	0.510	/	0.711
K	3.610	/	4.110
L	/	/	/
J	/	/	/
P	1 REF		
E1	3.375	/	3.780
θ	/	/	/
R	/	/	/

Suggested Pad Layout(Unit:mm)



迴流焊建議曲線：



IPC/JEDEC J-STD-020E, Figure 5-1 Classification Profile (Not to scale)

迴流焊建議曲線：設定說明：

Table 5-2 Classification Profiles

Profile Feature	Sn-Pb Eutectic Assembly
Preheat/Soak	
Temperature Min (T_{smin})	100 °C
Temperature Max (T_{smax})	150 °C
Time (t_s) from (T_{smin} to T_{smax})	60-120 seconds
Ramp-up rate (T_L to T_p)	3 °C/second max.
Liquidous temperature (T_L)	183 °C
Time (t_L) maintained above T_L	60-150 seconds
Peak package body temperature (T_p)	For users T_p must not exceed the Classification temp in Table 4-1. For suppliers T_p must equal or exceed

迴流焊峰值參考表：4-1 有鉛，4-2 無鉛

Table 4-1 SnPb Eutectic Process – Classification Temp

Package Thickness	Volume mm ³ <350
0.5 mm	235 °C

Table 4-2 Pb-Free Process – Classification Temperatures

Package Thickness	Volume mm ³ <350	Volume mm ³ 350 - 2000
<1.6 mm	260 °C	260 °C

手動焊錫或波峰焊參考條件：

TABLE 2036-1: Test conditions.

Test Condition	Solder Technique simulation	Temperature (°C)	Time (s) (at temp.)	Temperature (°C)
A	Solder iron	350 ± 10 (solder iron temp)	4 - 5	
B	Dip	260 ± 5 (solder temp)	10 ± 1	
C	Wave: Topside	260 ± 5 (solder temp)	20 ± 1	Preheat 100 °C
D	Wave: Bottom-side	260 ± 5 (solder temp)	10 ± 1	Preheat 100 °C
E	Vapor phase reflow	215 ± 5	60 ± 5	

MIL-STD-883G Method 2036